

PATENT ABSTRACTS OF JAPAN

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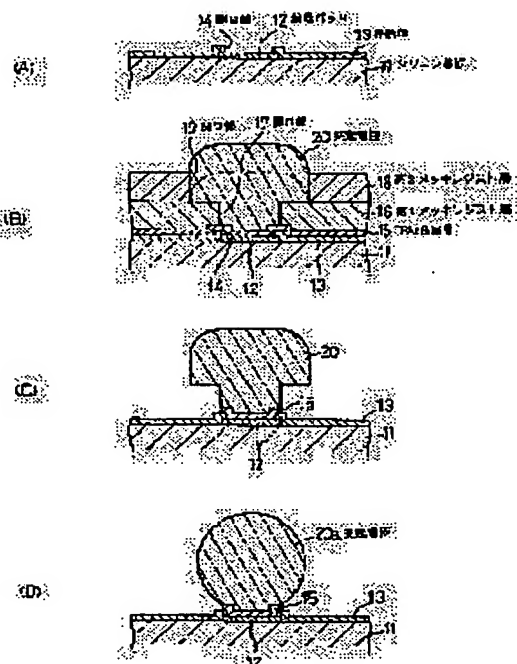
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(54) FORMATION OF PROJECTED ELECTRODE

(57)Abstract:

PROBLEM TO BE SOLVED: To realize formation of a fine pitch of projected electrodes even when the substantially-spherical, projected electrodes made of solder are made higher in their height.

SOLUTION: First and second plating resist layers 16 and 18 are formed on an underlying metallic layer 15 and then electroplating with solder is carried out. Since an opening 19 in the second plating resist layer 18 is larger than an opening 17 in the first plating resist layer 16, this causes the plating solder to be isotropically deposited within the opening 19 of the second resist layer 18 as shown by a dotted line in (B). Continuation of such isotropical deposition causes a top of a projected electrode 20 formed within the openings 17 and 19 of the first and second resist layers 16 and 18 to build up upwardly of the opening 19 of the second resist layer 18. In this case, a parasol part having such a mushroom shape as shown by a dotted line in (B) is restricted at its periphery by an inner wall of the opening 19 of the second resist layer 18, thus preventing further expansion of the parasol shape.



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